

# S1NBC80-7062

## Bridge Diodes

800V, 1.5A

### Feature

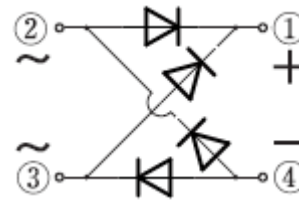
- Small SMD (There is also DIP)
- High  $I_{FSM}$
- Pin-distance 3.4mm for isolation
- Pb free terminal
- RoHS:Yes

### OUTLINE

Package (House Name): 1NA



### Equivalent circuit



### Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperature	T <sub>stg</sub>		-55 to 150	°C
Junction temperature	T <sub>j</sub>		-55 to 150	°C
Repetitive peak reverse voltage	V <sub>RRM</sub>		800	V
Average forward current	I <sub>F(AV)</sub>	50Hz sine wave, Resistance load, On glass-epoxy substrate Tl=105°C	1.5	A
Average forward current	I <sub>F(AV)</sub>	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=27°C ※	1	A
Average forward current	I <sub>F(AV)</sub>	50Hz, Sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C ※	0.84	A
Surge forward current	I <sub>FSM</sub>	50Hz sine wave, Non-repetitive 1 cycle peak value, T <sub>j</sub> =25°C	60	A
Current squared time	I <sup>2</sup> t	1ms ≤ tp < 10ms, T <sub>j</sub> =25°C, per diode	10	A <sup>2</sup> s

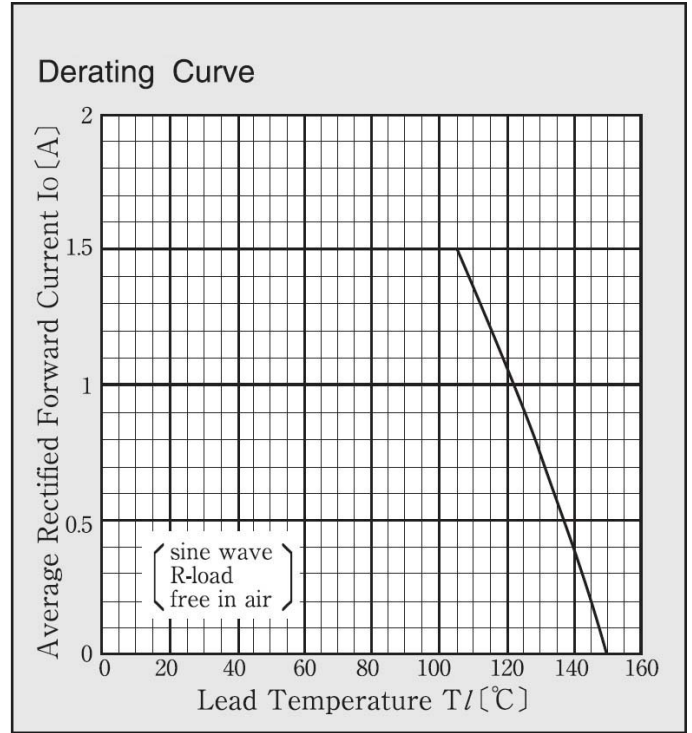
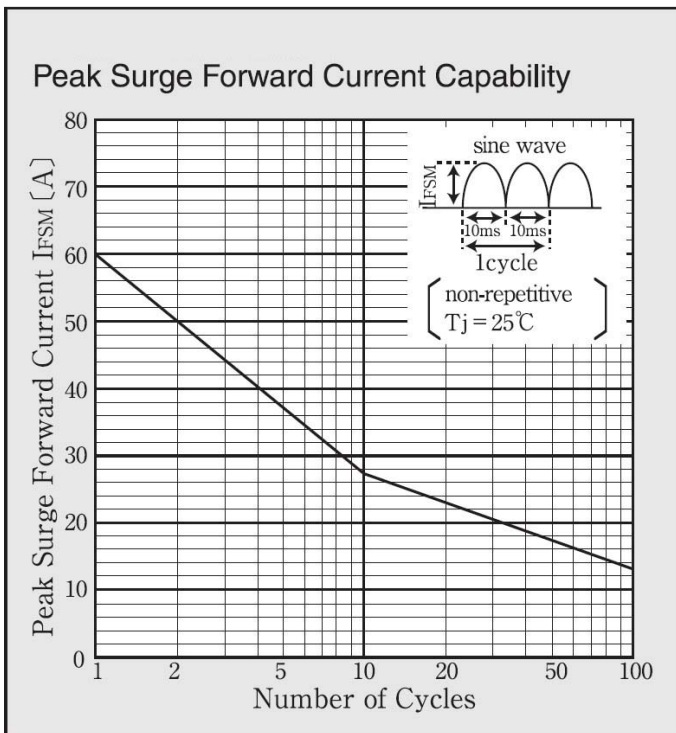
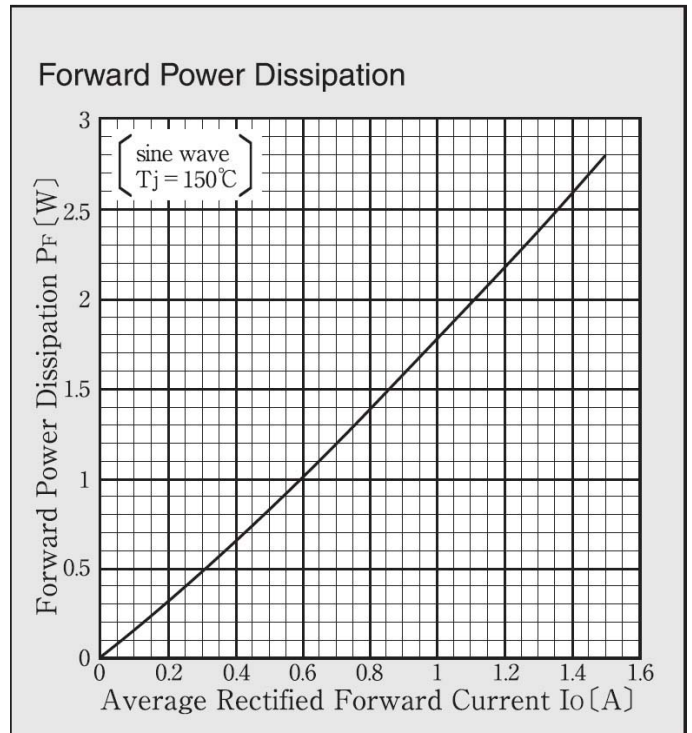
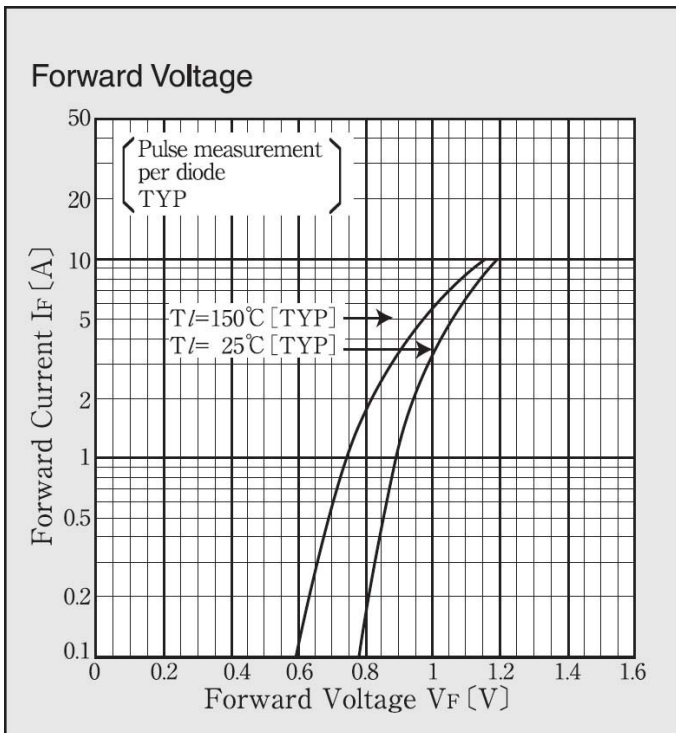
※ : See the original Specifications

**Electrical Characteristics** (unless otherwise specified : Tl=25°C)

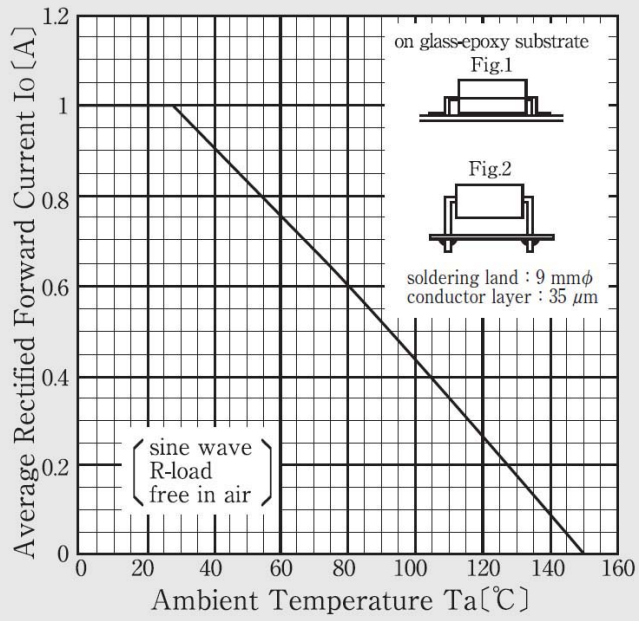
Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	$V_F$	$I_F=0.75A$ , Pulse measurement, per diode			1.05	V
Reverse current	$I_R$	$V_R=800V$ , Pulse measurement, per diode			10	$\mu A$
Thermal resistance	$R_{th(j-l)}$	Junction to lead, On glass-epoxy substrate			15	$^{\circ}C/W$
Thermal resistance	$R_{th(j-a)}$	Junction to ambient, On glass-epoxy substrate *			68	$^{\circ}C/W$
Thermal resistance	$R_{th(j-a)}$	Junction to ambient, On glass-epoxy substrate *			84	$^{\circ}C/W$

\* :See the original Specifications

# CHARACTERISTIC DIAGRAMS

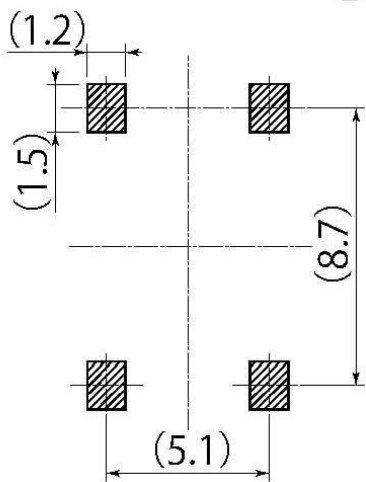
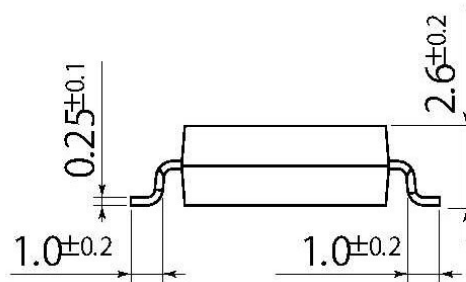
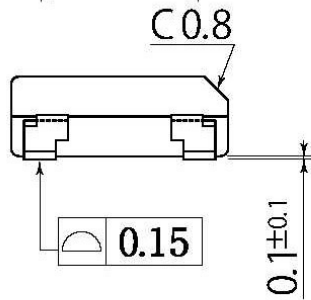
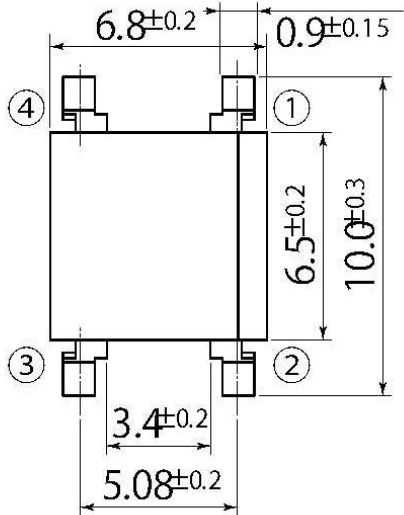


### Derating Curve



C6

JEDEC Code	-
JEITA Code	-
House Name	1NA(SMD)



Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

## Notes

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